
APPROXIMATE MODELLING PROCEDURES FOR RAPID ANALYSIS AND DESIGN

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Microelectronics Heat Transfer Laboratory

Overview

- What is modelling?
- How can approximate modelling methods be used to understand thermal behaviour in electronics applications
- Modelling procedures: as applied to heat sinks
- Other potential applications



Modelling Alternatives

- Experimental Methods
 - prototype testing
 - empirically-based correlations
- Numerical Methods
 - approximate the governing equations over a finite, discretized domain
- Analytical Methods
 - closed form solutions
 - approximate methods



Why Use Approximate Methods?

- Fast, accurate and easy to use
- Minimal hardware requirements
- Ideal for preliminary design studies
 - material selection
 - component selection and placement
 - trade-off studies
- Optimization studies
- Concurrent design

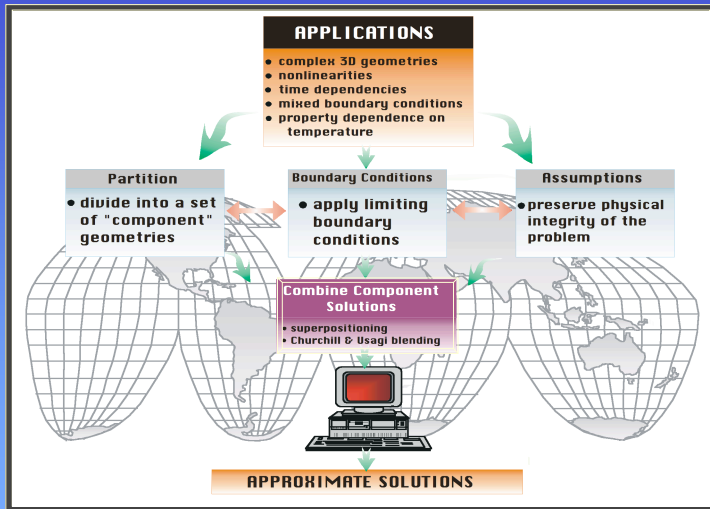


Perceived Limitations

- Limited range of applications
- Cannot be used for complex geometries
- Cannot be used with mixed or non-uniform boundary conditions
- Simplifying assumptions provide inaccurate solutions



Modelling Approach



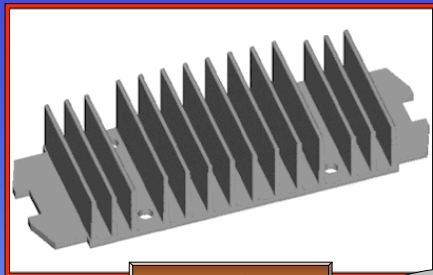
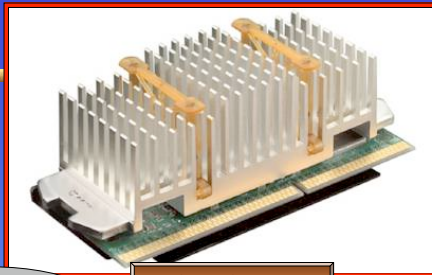


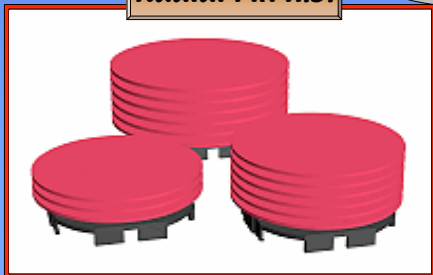
Plate Fin H.S.



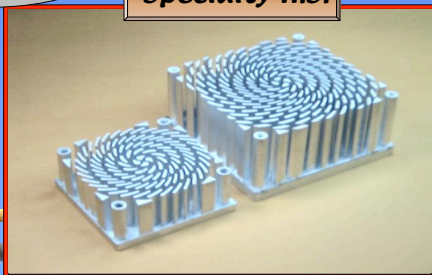
Pin Fin H.S.

**Heat Sink
Alternatives**

Radial Fin H.S.



Specialty H.S.



Heat Sink Model

- Plate fin heat sink
- Natural convection
- Vertical orientation
- Isothermal
- Steady state
- Working fluid is air



Modelling Procedure

Given: dimensions & temperature

Find: Nu_b vs. Ra_b

$$= \frac{hb}{k_f} = \frac{g\beta\Delta T b^3}{\alpha\nu} \cdot \frac{b}{L}$$

Exterior surfaces

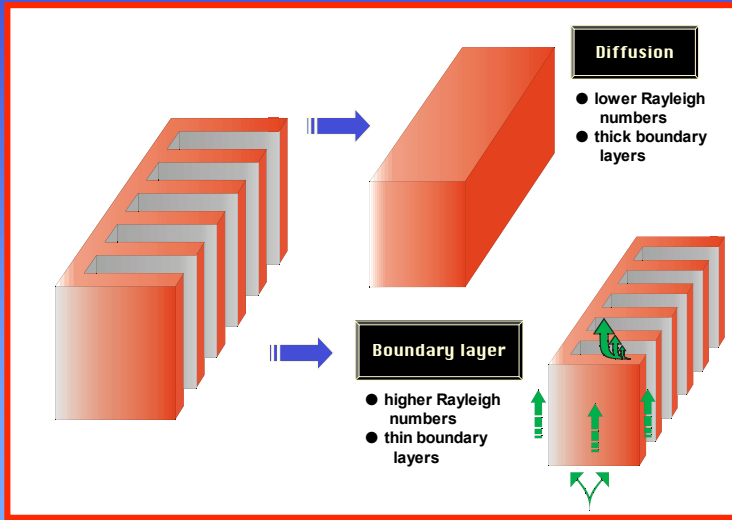
- fins : top, bottom, ends & tip
- base plate: top, bottom, ends and back

Interior surfaces

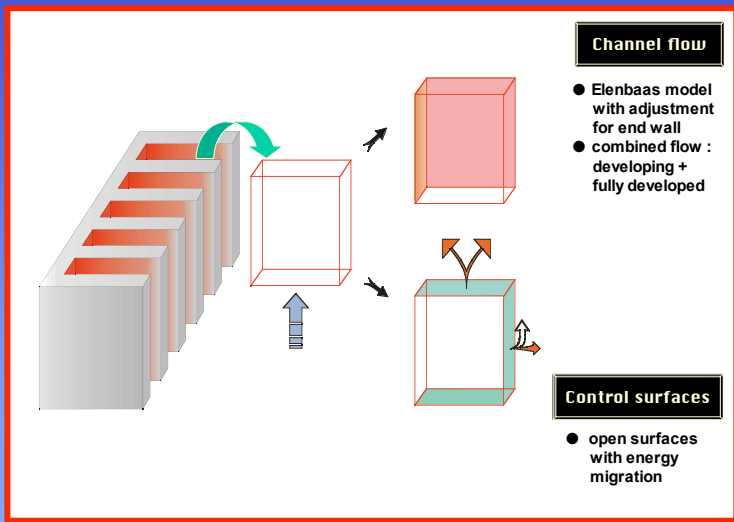
- fins : side walls
- channel base



Exterior Surfaces



Interior Surfaces

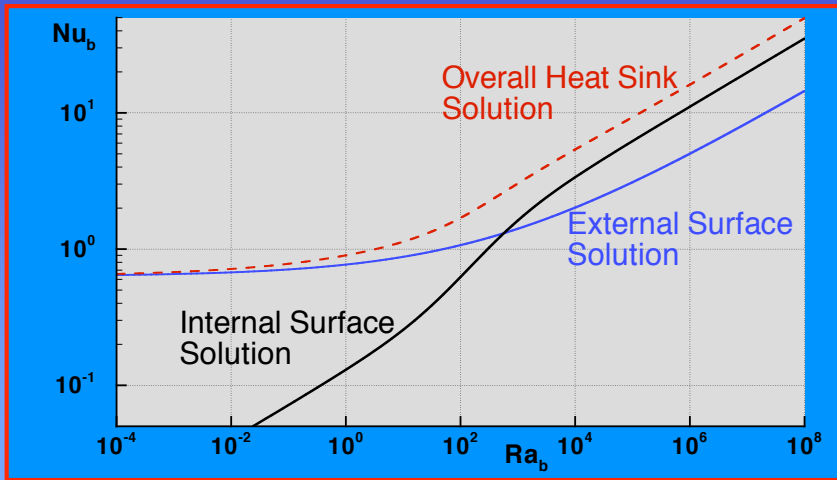


Comprehensive Model

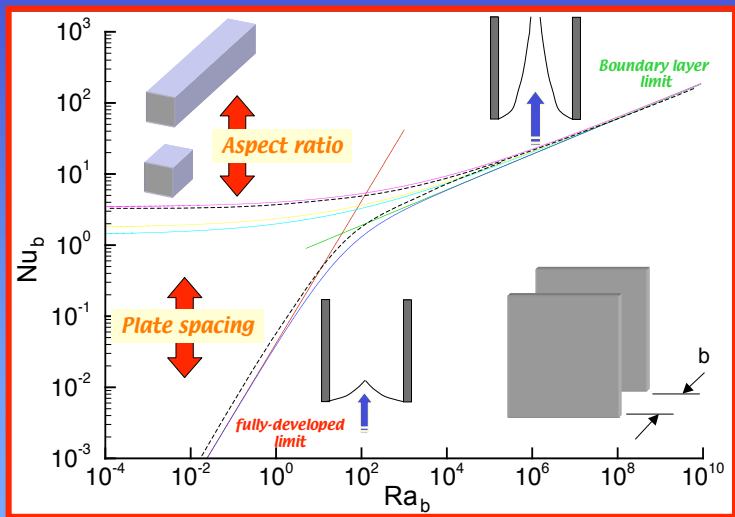
$$Nu = \underbrace{Nu_0}_{\text{diffusion}} + \frac{1}{\underbrace{\frac{1}{Nu_2} + \frac{1}{Nu_3 + Nu_4}}_{\text{channel flow}}} + \underbrace{Nu_1}_{\text{external boundary layer flow}}$$

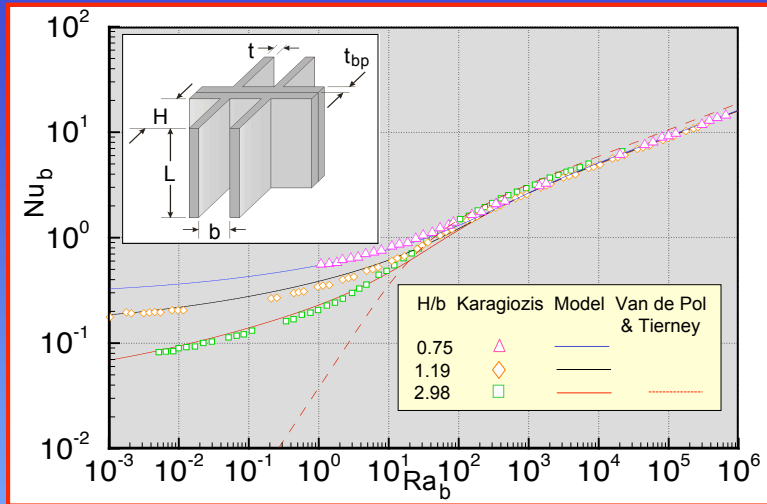


Total Composite Solution



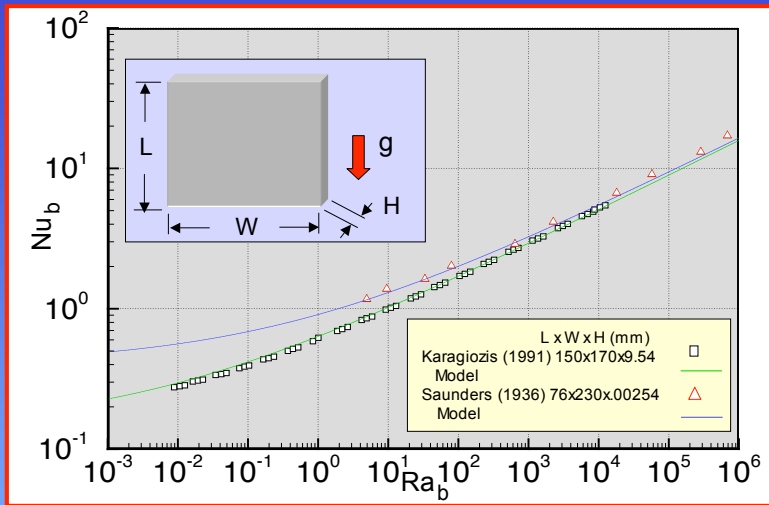
Modelling Domain





$$Nu = Nu_0 + \left\{ Nu_2^{-2} + [Nu_3 + Nu_4]^{-2} \right\}^{-1/2} + Nu_1$$



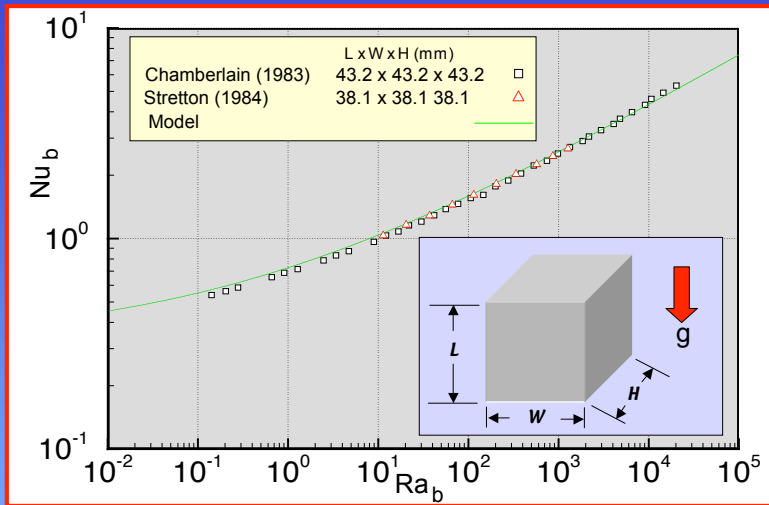


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How Do We Use These Results?

dimensionless
heat
transfer
coefficient

dimensionless flow
parameter

- *If max. θ_{j-c} changes \Rightarrow what is the max. P_{diss} dissipated*
- *For a given θ_{j-c} \Rightarrow what is the max. θ_{j-c} of the heat sink or the package junction*
- *How do changes in geometry affect θ_{j-c} and θ_{c-a}*



Future Work

Goal: Develop a comprehensive model to find the best heat sink design given a limited set of design constraints

Physical Design

- heat sink type
- material
- weight
- dimensions
- surface finish

Thermal

- maximum volume
- boundary conditions
- max. allowable temp.
- orientation
- flow mechanism

Cost

- labour
- manufacturing
- material

Standards

- noise
- exposure to touch



Other Examples of Approximate Models

<i>Applications</i>	<i>Asymptotic Limits</i>	
<i>Heat & Mass Transfer</i>		
● <i>Boundary layer flow</i>	laminar	turbulent
● <i>Channel flow</i>	fully developed flow	boundary layer flow
● <i>External flow</i>	diffusion	boundary layer flow
● <i>Internal flow</i>	fully developed flow	developing flow
● <i>Enclosures</i>	diffusion	boundary layer flow
● <i>Transient conduction</i>	short time	steady state
● <i>Radiation</i>	opaque	transparent
● <i>Steady conduction at nano-scales</i>	rarefied	continuum
<i>Moving Sources</i>	stationary	fast moving
<i>Elasto-plastic contacts</i>	elastic	plastic



Summary

- Approximate models offer superior speed of execution and ease of use over most conventional modelling methods
- Analytical modelling can be used for a wide range of applications previously considered to be too complex



The End



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